



(51) International Patent Classification:

H01S 5/022 (2006.01) H01S 5/062 (2006.01)
H01S 5/042 (2006.01) H01S 5/42 (2006.01)

(21) International Application Number:

PCT/EP2013/075005

(22) International Filing Date:

28 November 2013 (28.11.2013)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

12196474.6 11 December 2012 (11.12.2012) EP

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JP, KE, KG, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ,

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(54) Title: INTERCONNECT STRUCTURE FOR COUPLING AN ELECTRONIC UNIT AND AN OPTICAL UNIT, AND OPTOELECTRONIC MODULE

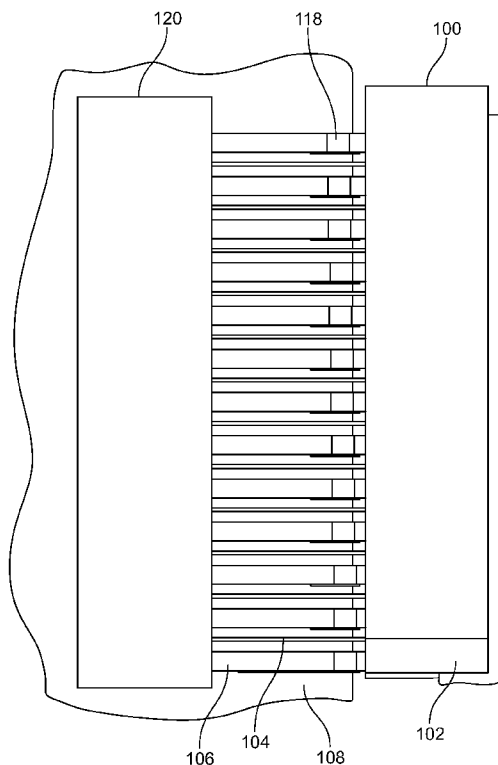


Fig. 3

(57) Abstract: The present invention relates to an interconnect structure for coupling an electronic unit for outputting and/or receiving electric signals, and an optical unit for converting said electric signals into optical signals and/or vice versa. The present invention also relates to an optoelectronic module comprising such an interconnect structure. The interconnect structure comprises an electrically insulating substrate and at least one pair of transmission leads (104, 106) to be coupled between said electronic unit (120) and said optical unit (100), a first lead (104) being operable as a signal line, a second lead (106) being operable as a ground line, wherein said second lead (106) is formed to have a lower impedance than said first lead (104).



TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, **Published:**

EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU,

LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK,

SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,

GW, KM, ML, MR, NE, SN, TD, TG).

— *with international search report (Art. 21(3))*